

60V COMPLEMENTARY ENHANCEMENT MODE MOSFET H-BRIDGE
Product Summary

Device	$V_{(BR)DSS}$	$R_{DS(ON)} \text{ Max}$	$I_D \text{ Max}$ $T_A = 25^\circ\text{C}$
N-Channel	60V	100mΩ @ $V_{GS} = 10\text{V}$	4.1A
		120mΩ @ $V_{GS} = 4.5\text{V}$	3.7A
P-Channel	-60V	170mΩ @ $V_{GS} = -10\text{V}$	3.1A
		250mΩ @ $V_{GS} = -4.5\text{V}$	2.6A

Description

This new generation complementary MOSFET H-Bridge features low on-resistance achievable with low gate drive.

Applications

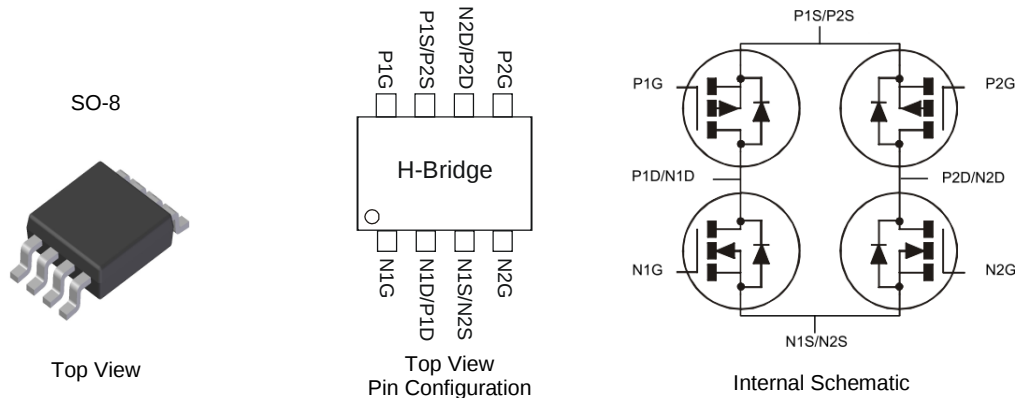
- DC Motor Control
- DC-AC Inverters

Features

- 2 x N + 2 x P Channels in a SOIC Package
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

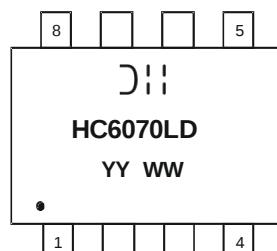
Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish – Matte Tin Annealed over Copper Leadframe.
Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.074 grams (Approximate)


Ordering Information (Note 4)

Part Number	Case	Packaging
DMHC6070LSD-13	SO-8	2,500/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information


DII = Manufacturer's Marking
 HC6070LD = Product Type Marking Code
 YYWW = Date Code Marking
 YY = Year (ex: 16 = 2016)
 WW = Week (01 - 53)

Maximum Ratings – N-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	60	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 5) V _{GS} = 10V	Steady State	T _A = +25°C T _A = +70°C	I _D	3.1 2.5	A
	t<10s	T _A = +25°C T _A = +70°C	I _D	4.1 3.3	A
Maximum Continuous Body Diode Forward Current (Note 5)			I _S	2.0	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	15	A
Avalanche Current (Note 6) L = 0.1mH			I _{AS}	12	A
Avalanche Energy (Note 6) L = 0.1mH			E _{AS}	8	mJ

Maximum Ratings – P-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V _{DSS}	-60	V
Gate-Source Voltage			V _{GSS}	±20	V
Continuous Drain Current (Note 5) V _{GS} = -10V	Steady State	T _A = 25°C T _A = 70°C	I _D	-2.4 -1.9	A
	t<10s	T _A = 25°C T _A = 70°C	I _D	-3.1 -2.5	A
Maximum Continuous Body Diode Forward Current (Note 5)			I _S	-2.0	A
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	-12	A
Avalanche Current (Note 6) L = 0.1mH			I _{AS}	-12	A
Avalanche Energy (Note 6) L = 0.1mH			E _{AS}	8	mJ

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)		P _D	1.6	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R _{θJA}	75	°C/W
	t<10s		45	
Thermal Resistance, Junction to Case (Note 5)		R _{θJC}	11	
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics – N-Channel (@T_A = +25°C, unless otherwise specified.)

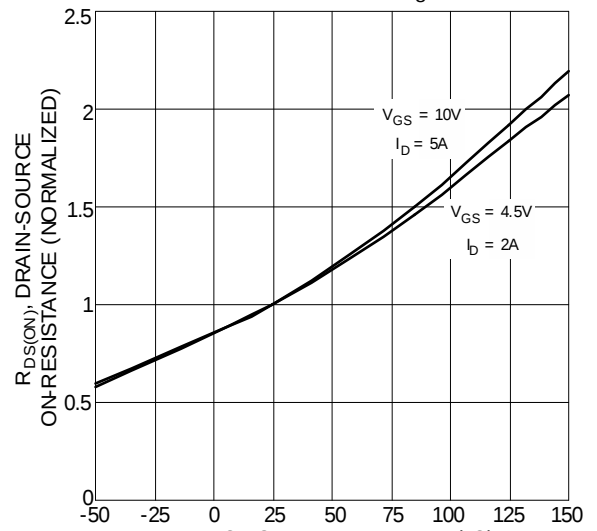
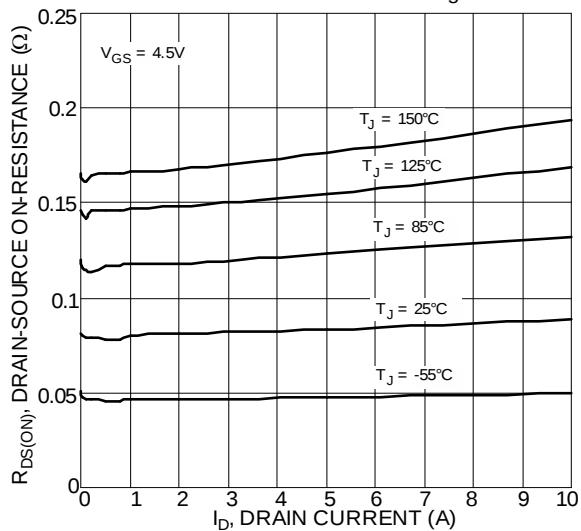
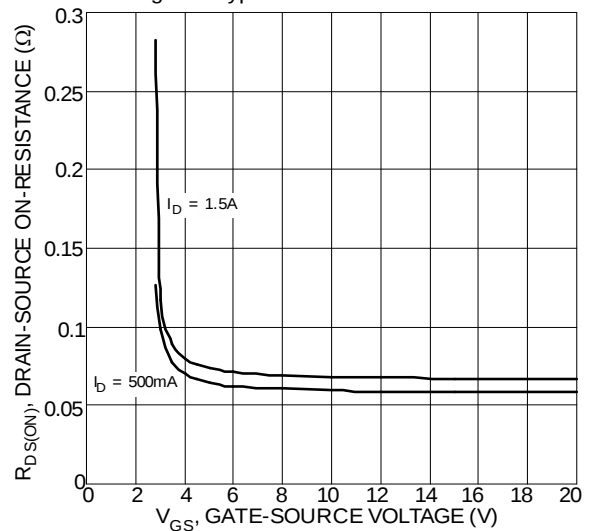
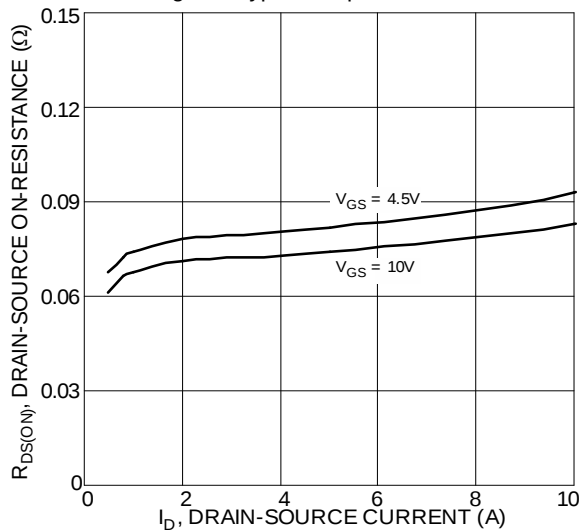
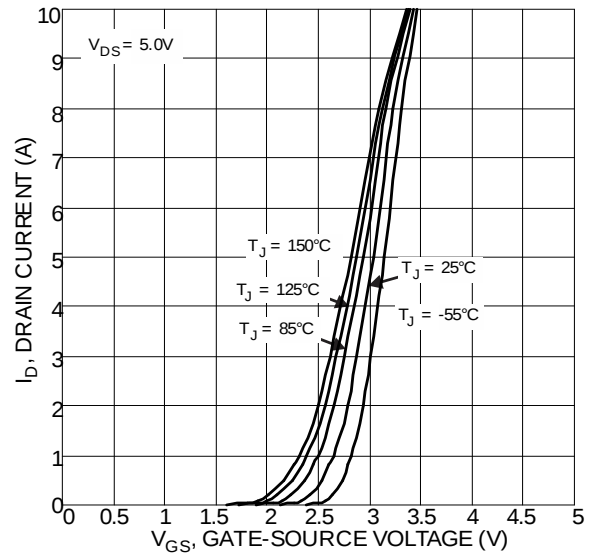
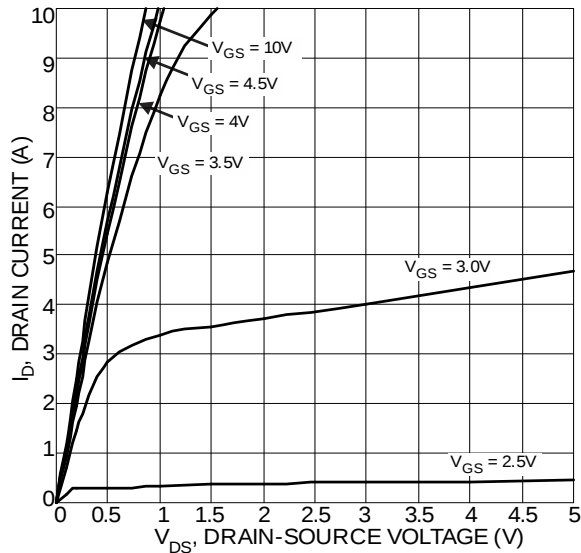
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	60	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 60V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	1.0	—	3.0	V	I _D = 250μA, V _{DS} = V _{GS}
Static Drain-Source On-Resistance	R _{DS(ON)}	—	60	100	mΩ	V _{GS} = 10V, I _D = 1.0A
			70	120		V _{GS} = 4.5V, I _D = 0.5A
Diode Forward Voltage	V _{SD}	—	0.8	1.2	V	V _{GS} = 0V, I _S = 3A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{ISS}	—	731	—	pF	V _{DS} = 20V, V _{GS} = 0V f = 1MHz
Output Capacitance	C _{OSS}	—	34	—		
Reverse Transfer Capacitance	C _{RSS}	—	23	—		
Gate resistance	R _G	—	1.3	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge	Q _G	—	5.2	—	nC	V _{GS} = 4.5V V _{DS} = 30V I _D = 3A
Total Gate Charge	Q _G	—	11.5	—		
Gate-Source Charge	Q _{GS}	—	2.1	—		
Gate-Drain Charge	Q _{GD}	—	1.5	—		
Turn-On Delay Time	t _{D(ON)}	—	9.6	—	ns	V _{DD} = 30V, V _{GS} = 10V R _L ≅ 50Ω, R _G ≅ 20Ω
Turn-On Rise Time	t _R	—	11	—		
Turn-Off Delay Time	t _{D(OFF)}	—	61	—		
Turn-Off Fall Time	t _F	—	21	—		
Body Diode Reverse Recovery Time	t _{RR}	—	10.5	—	ns	I _S = 1.0A, dI/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _{RR}	—	4.0	—	nC	I _S = 1.0A, dI/dt = 100A/μs

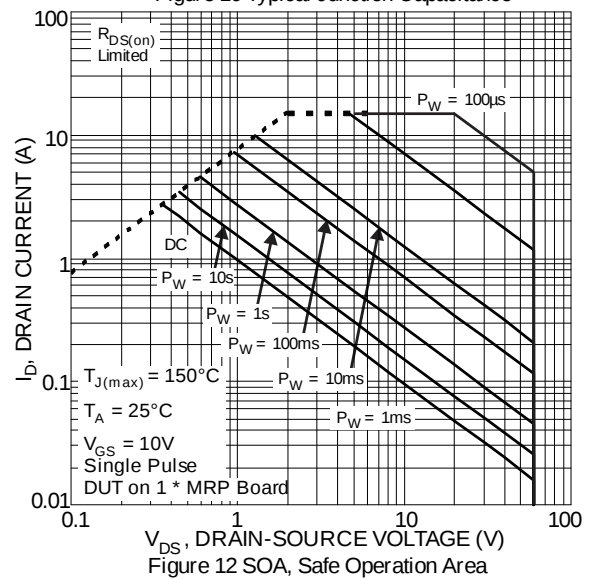
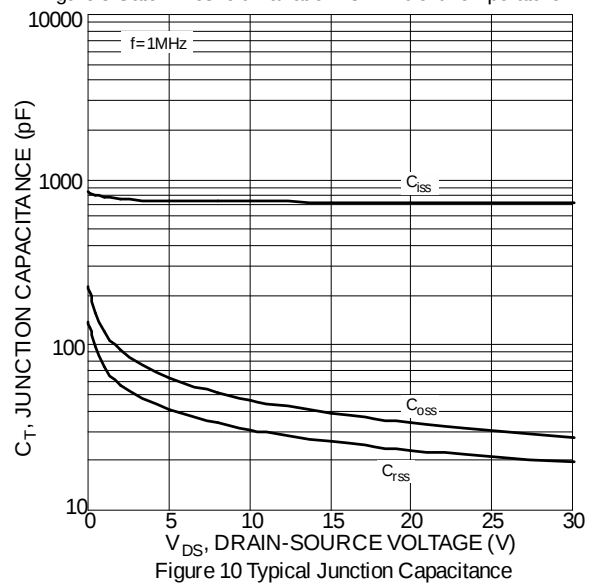
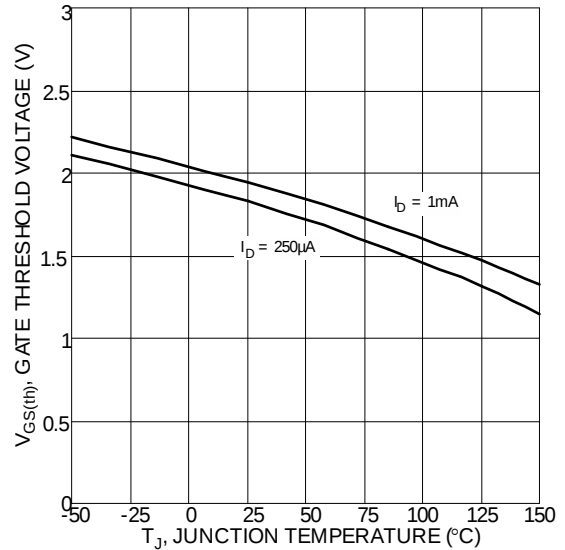
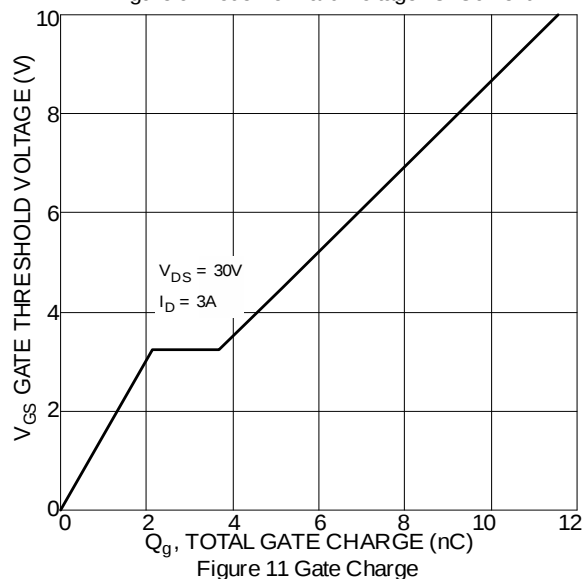
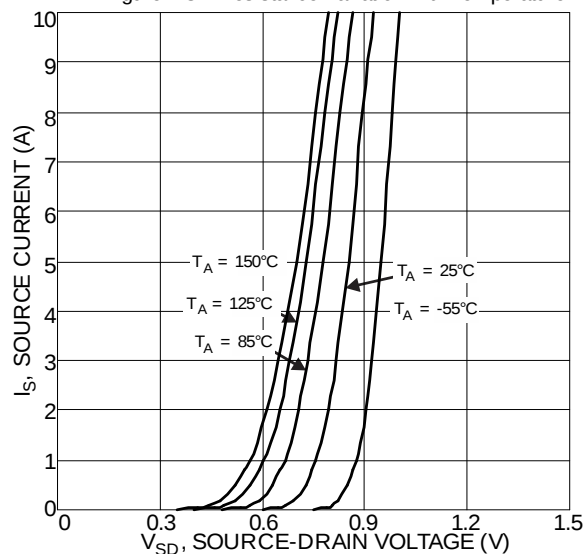
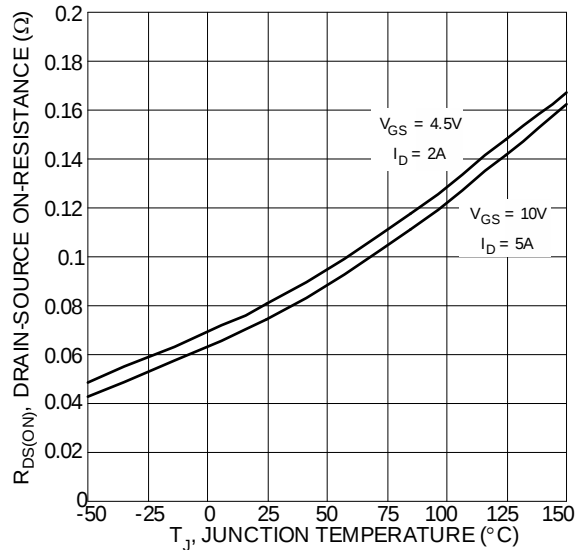
Electrical Characteristics – P-Channel (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV _{DSS}	-60	—	—	V	V _{GS} = 0V, I _D = -250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	-1	μA	V _{DS} = -60V, V _{GS} = 0V
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	V _{GS(TH)}	-1	—	-3	V	V _{DS} = V _{GS} , I _D = -250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	120	170	mΩ	V _{GS} = -10V, I _D = -1.0A
			170	250		V _{GS} = -4.5V, I _D = -0.5A
Diode Forward Voltage	V _{SD}	—	-0.8	-1.2	V	V _{GS} = 0V, I _S = -2A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C _{ISS}	—	618	—	pF	V _{DS} = -20V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	C _{OSS}	—	36	—		
Reverse Transfer Capacitance	C _{RSS}	—	26	—		
Gate resistance	R _G	—	13	—	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz
Total Gate Charge	Q _G	—	4.3	—	nC	V _{GS} = -4.5V V _{DS} = -30V I _D = -2A
Total Gate Charge	Q _G	—	8.9	—		
Gate-Source Charge	Q _{GS}	—	1.4	—		
Gate-Drain Charge	Q _{GD}	—	1.7	—		
Turn-On Delay Time	t _{D(ON)}	—	7.6	—	ns	V _{DD} = -30V, V _{GS} = -10V R _L ≅ 50Ω, R _G ≅ 20Ω
Turn-On Rise Time	t _R	—	11.6	—		
Turn-Off Delay Time	t _{D(OFF)}	—	79.8	—		
Turn-Off Fall Time	t _F	—	37.8	—		
Body Diode Reverse Recovery Time	t _{RR}	—	10.8	—	ns	I _S = -1.0A, dI/dt = 100A/μs
Body Diode Reverse Recovery Charge	Q _{RR}	—	3.8	—	nC	I _S = -1.0A, dI/dt = 100A/μs

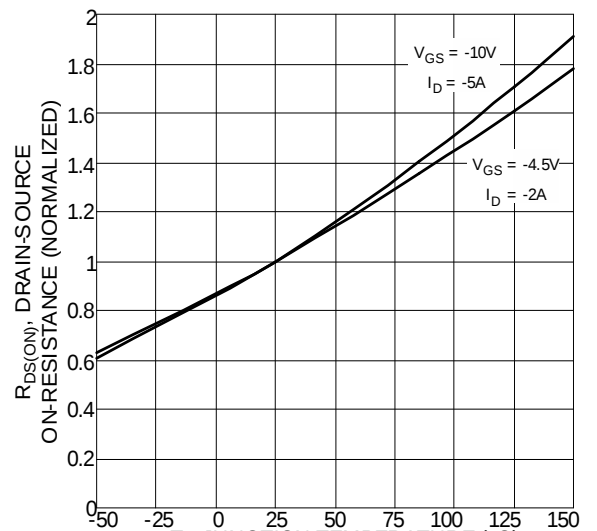
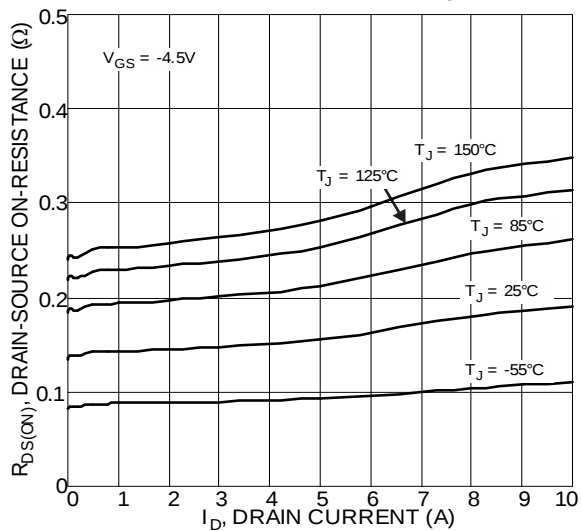
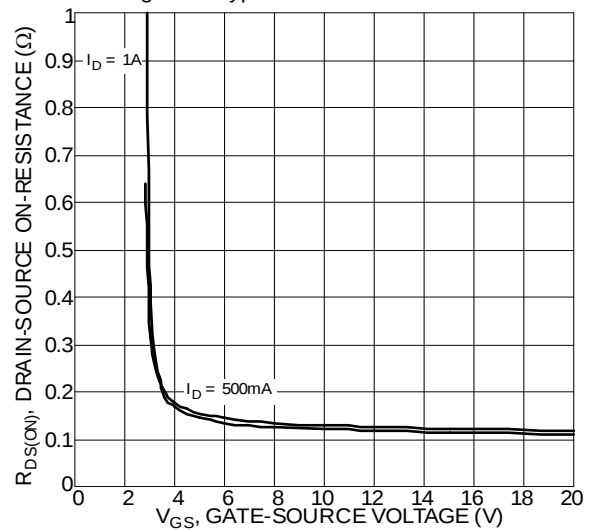
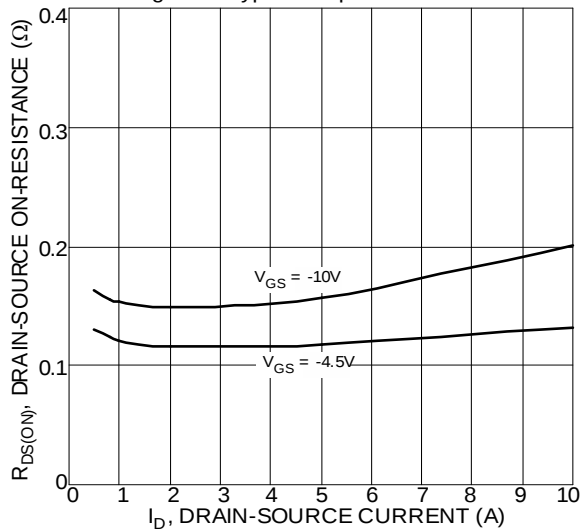
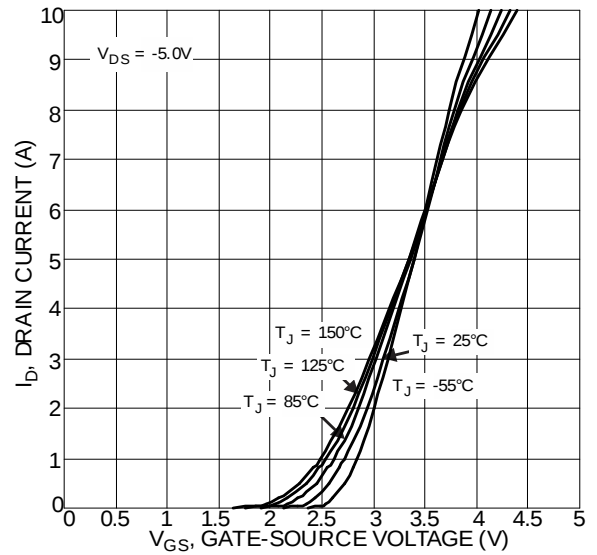
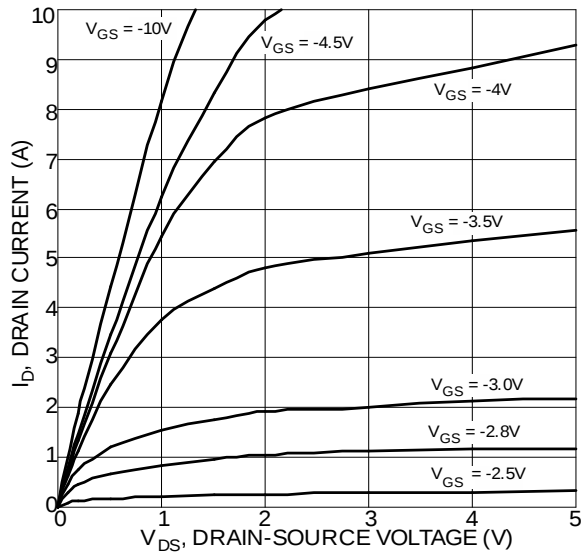
- Notes: 5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
6. I_{AS} and E_{AS} rating are based on low frequency and duty cycles to keep T_J = +25°C
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.

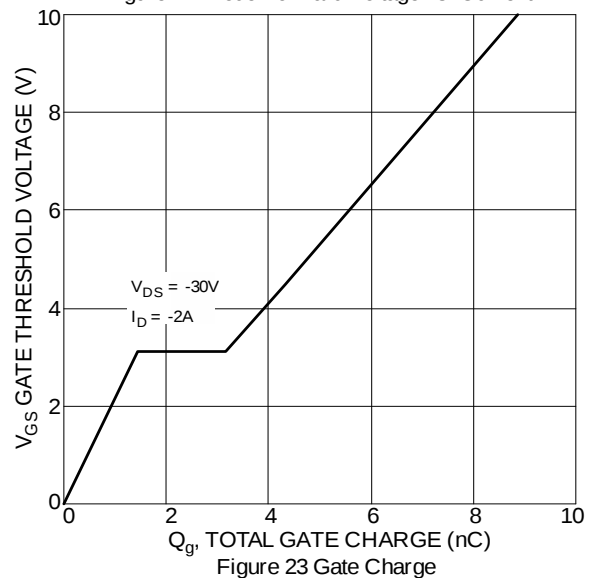
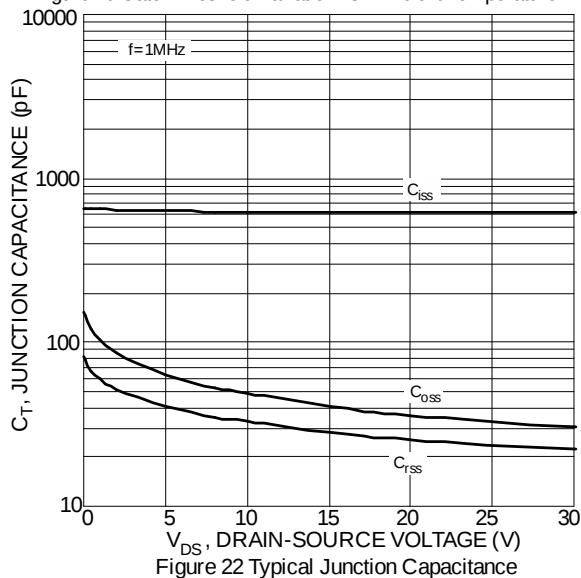
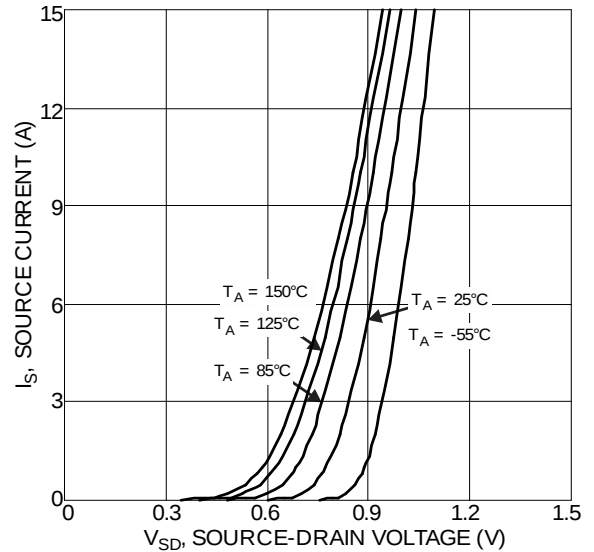
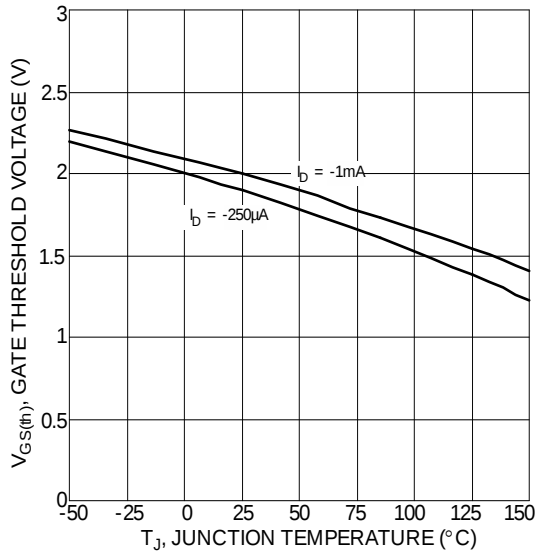
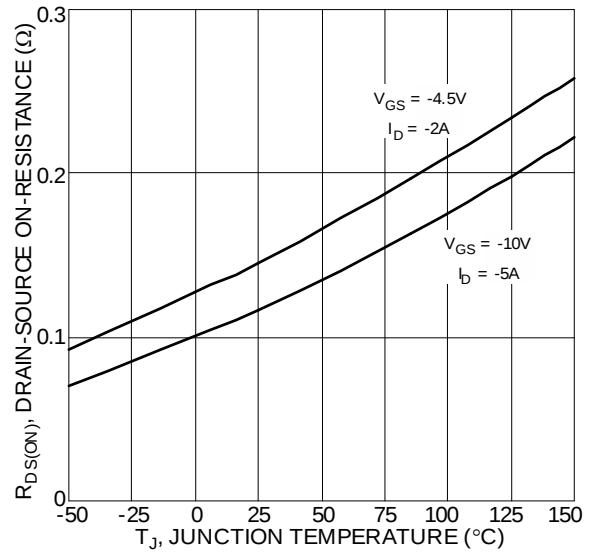
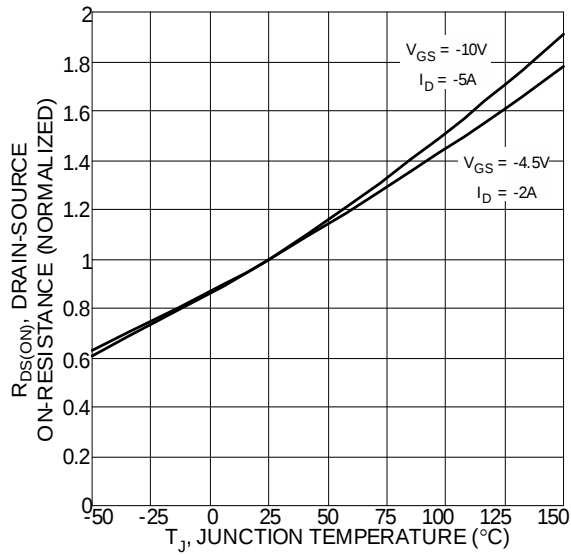
Typical Performance Characteristics – N-Channel

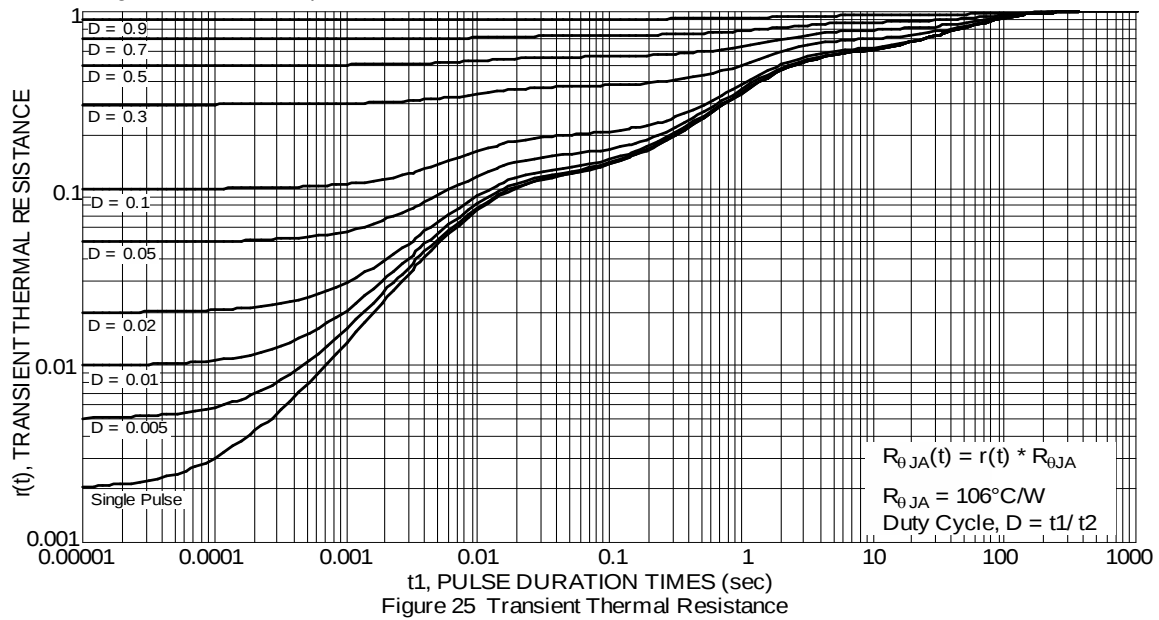
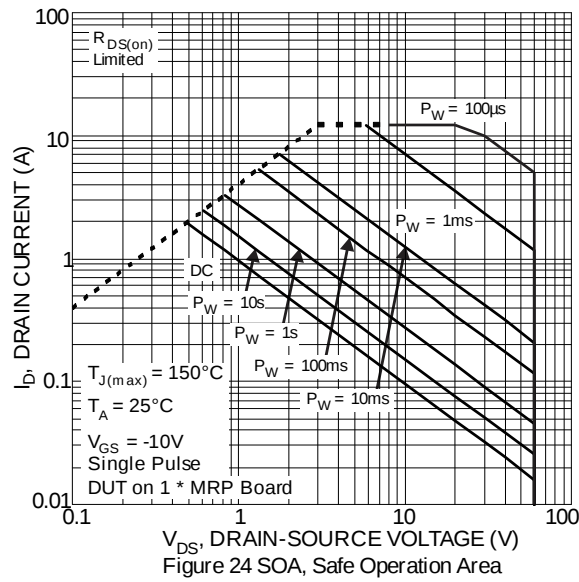




Typical Performance Characteristics – P-Channel



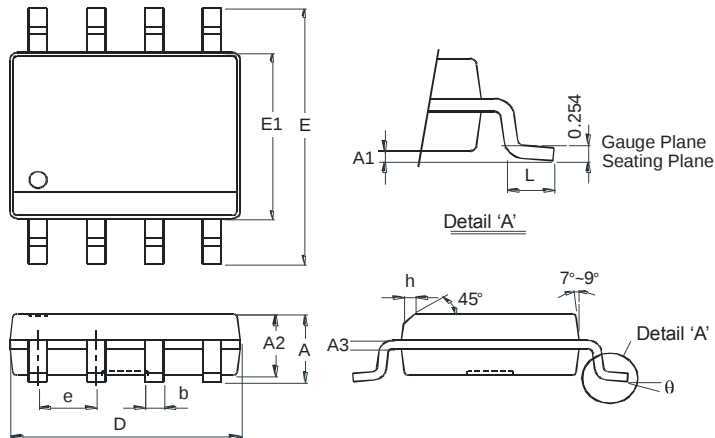




Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8

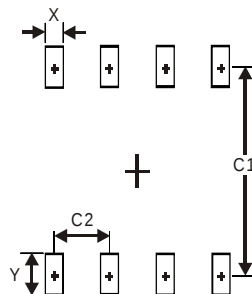


SO-8		
Dim	Min	Max
A	—	1.75
A1	0.10	0.20
A2	1.30	1.50
A3	0.15	0.25
b	0.3	0.5
D	4.85	4.95
E	5.90	6.10
E1	3.85	3.95
e	1.27 Typ	
h	—	0.35
L	0.62	0.82
θ	0°	8°
All Dimensions in mm		

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27

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